

# uPOL Module

MUN24AD01-SH

# 1A, High Efficiency uPOL Module

#### **FEATURES:**

- High Density uPOL Module
- 1A Output Current
- Input Voltage Range from 4.5V to 28V
- Output Voltage Range from 2V to 8.5V
- 91% Peak Efficiency (@Vin=12V)
- Automatic Power Saving/PWM Mode
- Switching Frequency 420KHz
- Protections (OCP: Non-latching, OTP)
- Internal Soft Start
- Compact Size: 3.5mm\*3.5mm\*1.7mm(Max)
- Pb-free for RoHS compliant
- MSL 2, 260°C Reflow

#### **APPLICATIONS:**

- ADAS Camera/Radar Modules
- LED Modules
- Infotainment/Instrument Cluster ECU

### **GENERAL DESCRIPTION:**

The uPOL module is non-isolated DC-DC converters that can deliver up to 1A of output current. The PWM switching regulator, high frequency power inductor are integrated in one hybrid package. It only needs some passive component to use this uPOL module easily.

The module has automatic operation with PWM mode and power saving mode according to loading. Other features include remote enable function, internal soft-start, non-latching over current protection.

The low profile and compact size package (3.5mm  $\times$  3.5mm  $\times$  1.7mm) is suitable for automated assembly by standard surface mount equipment. The uPOL module is Pb-free and RoHS compliant.

The wide input voltage range offers high tolerance to the extreme working conditions.

### **TYPICAL APPLICATION CIRCUIT & PACKAGE SIZE:**

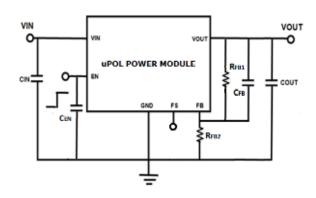


FIG.1 TYPICAL APPLICATION CIRCUIT

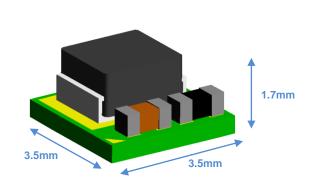


FIG.2 HIGH DENSITY POWER MODULE

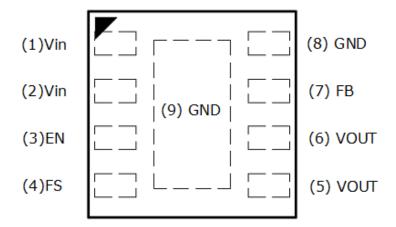


# **ORDER INFORMATION:**

| Part Number  | Ambient Temp. Range<br>(°C) | Package<br>(Pb-Free) | MSL     | Note |
|--------------|-----------------------------|----------------------|---------|------|
| MUN24AD01-SH | 85                          | DFN                  | Level 2 | -    |

| Order Code   |  | Packing       | Quantity |
|--------------|--|---------------|----------|
| MUN24AD01-SH |  | Tape and reel | 1000     |

# **PIN CONFIGURATION:**



**TOP VIEW** 

# PIN DESCRIPTION:

| Symbol   | Pin No. | Description   |
|--|---------|---|
| VIN  | 1, 2    | Power input pin. Place the ceramic type input capacitor as closely as possible to this pin. At least 10uF input capacitance is needed.  |
| On/Off control pin for module. Pull high to turn on. Pull low EN 3 It is necessary for adding a 0.1uF ceramic cap between EN Do not leave this pin floating. |         | On/Off control pin for module. Pull high to turn on. Pull low to turn off. It is necessary for adding a 0.1uF ceramic cap between EN and GND. Do not leave this pin floating. |
|  |         | Frequency programming pin. The pin left floating if this function is not used   |
| VOUT   | 5, 6    | Power output pin. Place the output capacitors as closely as possible to this pin. At least 22uF output capacitance is needed.   |
| FB   | 7       | Feedback input. Connect an external dividing resistor $R_{\text{FB1}}$ and $R_{\text{FB2}}$ , refer to TABEL 1 output voltage setting.  |
| GND  | 8, 9    | Power ground pin. Connect to thermal exposed pad of (9)GND for heat transferring.   |



# **ELECTRICAL SPECIFICATIONS:**

CAUTION: Do not operate at or near absolute maximum rating listed for extended periods of time. This stress may adversely impact product reliability and result in failures not covered by warranty.

| Parameter                          | Description  | Min. | Тур. | Max.  | Unit |
|------------------------------------|--|------|------|-------|------|
| ■ Absolute Maxim                   | uum Ratings  |      |      |       |      |
| VIN to GND                         |  | -0.2 | -    | +40.0 | V    |
| SW to GND                          |  | -0.2 |      | +40.0 | V    |
| EN to GND                          |  | -0.2 | -    | +40.0 | V    |
| FS to GND                          |  | -0.2 | -    | +40.0 | V    |
| FB to GND                          |  | -0.2 |      | +40.0 | V    |
| Tc                                 | Case Temperature of Inductor                         | -    | -    | +165  | °C   |
| Tj                                 | Junction Temperature                                 | -40  | -    | +150  | °C   |
| Tstg                               | Storage Temperature                                  | -40  | -    | +125  | °C   |
| ■ Recommendation Operating Ratings |  |      |      |       |      |
| VIN                                | Input Supply Voltage                                 | +4.5 | -    | +28.0 | V    |
| VOUT                               | Adjusted Output Voltage                              | +2.0 | -    | +8.5  | V    |
| Та                                 | Ambient Temperature                                  | -40  | -    | 85    | °C   |
| ■ Thermal Information              |  |      |      |       |      |
| Rth(j <sub>choke</sub> -a)         | Thermal resistance from junction to ambient (Note 1) | -    | 40   | -     | °C/W |

### NOTES:

1. Rth(j<sub>choke</sub>-a) is measured with the component mounted on an effective thermal conductivity test board on 0 LFM condition. The test board size is 30mm×30mm×1.6mm with 4 layers, 1 oz per layer. The test condition is complied with JEDEC EIJ/JESD 51 Standards.



# **ELECTRICAL SPECIFICATIONS: (Cont.)**

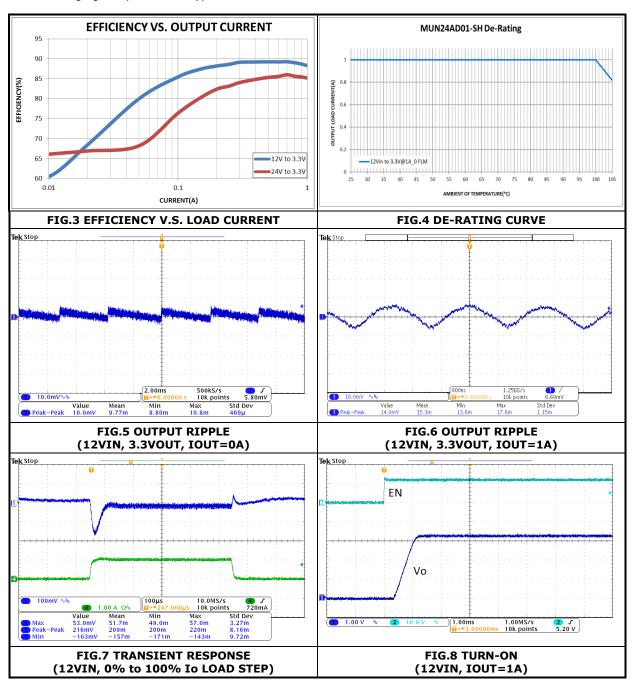
Conditions:  $T_A = 25$  °C, unless otherwise specified. Test Board Information:  $30 \text{mm} \times 30 \text{mm} \times 1.6 \text{mm}$ , 4 layers 1 oz. The output ripple and transient response measurement is short loop probing and 20 MegHz bandwidth limited.  $V_{10} = 12 \text{V}$ ,  $V_{10} = 10 \text{V}$ ,  $V_{$ 

| Symbol  | Parameter  | Conditions   | Min. | Тур. | Max. | Unit                  |
|---|--|--|------|------|------|-----------------------|
| ■ Inpu  | ıt Characteristics                                   |  |      | ľ    |      | •                     |
| I <sub>SD</sub> Input shutdown current        |  | EN = GND and no pull up resistance connect to VIN                    | -    | 2    | -    | uA                    |
| I <sub>IN</sub>                               | Input supply bias current                            | EN = VIN, Iout = 0A  | -    | 70   | -    | uA                    |
| Is  | Input supply current                                 | EN = VIN, Iout = 1A  |      | 0.46 |      | Α                     |
| ■ Outp  | out Characteristics                                  |  |      |      |      |                       |
| I <sub>OUT(DC)</sub>                          | Output continuous<br>current range                   |  | 0    | -    | 1    | А                     |
| V <sub>O(SET)</sub>                           | Ouput Voltage Set Point<br>At PWM Mode               | With 0.1% tolerance for external resistor used to set output voltage | -3   | -    | +3   | % V <sub>O(SET)</sub> |
| $\Delta V_{OUT}/\Delta V_{IN}$                | Line regulation accuracy                             | Vin = 8V to 16V, Iout = 1A   | -    | 0.5  | -    | % V <sub>O(SET)</sub> |
| $\Delta V_{\text{OUT}}/\Delta I_{\text{OUT}}$ | Load regulation accuracy                             | Iout = 0A to 1A  | -    | 3    | -    | % V <sub>O(SET)</sub> |
|   |  | 20MHz Bandwidth  | -    | -    | -    | -                     |
| $V_{OUT(AC)}$                                 | Output ripple voltage                                | IOUT = 0A  | ı    | 15   | -    | mVp-p                 |
|   |  | IOUT = 1A  | -    | 20   | -    | mVp-p                 |
| ■ Conf  | trol Characteristics                                 |  |      |      |      |                       |
| ОСР   | Protection Output Current                            |  | 2    | -    | 4    | А                     |
| ОТР   | Over temp protection                                 |  |      | 150  |      | °C                    |
| Fosc  | Oscillator frequency<br>( Frequency<br>programmable) |  | 340  | -    | 510  | KHz                   |
| $V_{ENL}$                                     | EN Low threshold                                     |  | 0.4  | -    | -    | V                     |
| V <sub>ENH</sub>                              | EN High Threshold                                    |  | -    | -    | 1.7  | V                     |
| UVLO Input under voltage lockout threshold    |  |  | -    | -    | 4.35 | V                     |



### **TYPICAL PERFORMANCE CHARACTERISTICS: 3.3 Vout**

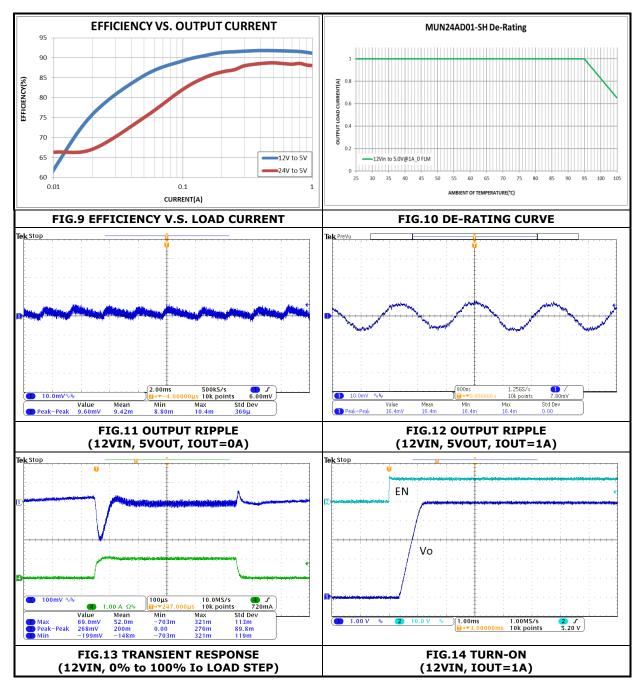
Conditions:  $T_A = 25$  °C, unless otherwise specified. Test Board Information:  $30\text{mm} \times 30\text{mm} \times 1.6\text{mm}$ , 4 layers 1 oz. The output ripple and transient response measurement is short loop probing and 20MegHz bandwidth limited. Fsw=420KHz, Cin=10uF/50V/1210/X7R, Cout= $22\text{uF}/16\text{V}/1210/\text{X7R}^*2$ , Cfb=100pF/50V/0402/X7R. The following figures provide the typical characteristic curves at 3.3Vout.





### **TYPICAL PERFORMANCE CHARACTERISTICS: 5.0 Vout**

Conditions:  $T_A = 25$  °C, unless otherwise specified. Test Board Information:  $30\text{mm} \times 30\text{mm} \times 1.6\text{mm}$ , 4 layers 1 oz. The output ripple and transient response measurement is short loop probing and 20MegHz bandwidth limited. Fsw=420KHz, Cin=10uF/50V/1210/X7R, Cout= $22\text{uF}/16\text{V}/1210/\text{X7R}^*2$ , Cfb=100pF/50V/0402/X7R. The following figures provide the typical characteristic curves at 5.0Vout.





### **APPLICATIONS INFORMATION: (Cont.)**

#### **SAFETY CONSIDERATIONS:**

Certain applications and/or safety agencies may require fuses at the inputs of power conversion components. Fuses should also be used when there is the possibility of sustained input voltage reversal which is not current limited. For greatest safety, we recommend a fast blow fuse installed in the ungrounded input supply line. The installer must observe all relevant safety standards and regulations. For safety agency approvals, install the converter in compliance with the end-user safety standard.

#### **INPUT FILTERING:**

The module should be connected to as low AC impedance source supply and a highly inductive source or line inductance can affect the stability of the module. Input capacitors must be placed directly to the input pin of the module, to minimize input ripple voltage and ensure module stability.

#### **OUTPUT FILTERING:**

To reduce output ripple and improve the dynamic response to as step load change, the additional capacitors at the output must be used. Low ESR ceramic capacitors are recommended to improve the output ripple and dynamic response of the module.

#### PROGRAMMING OUTPUT VOLTAGE:

The output voltage can be programmed by the dividing resistor  $R_{FB1}$  and  $R_{FB2}$  ( $R_{FB1}$  connected from FB to Vout;  $R_{FB2}$  connected from FB to GND). Assume  $R_{FB1}$  set 100 Kohm, the output voltage can be calculated as shown in Equation 1 and the resistance according to typical output voltage is shown in TABLE 1.

VOUT (V) = 
$$0.6 \times \left(1 + \frac{R_{FB1}}{R_{FB2}}\right)$$
 (EQ.1)

| Vout       | 2.5V    | 3.3V    | 5V      |
|------------|---------|---------|---------|
| RFB2 (Ohm) | 31.579k | 22.222k | 13.636k |

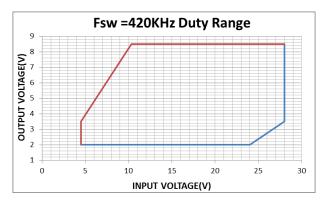
**TABLE 1: OUTPUT VOLTAGE SETTING** 

Note. R<sub>FB1</sub> maximum 200 Kohm, minimum 10 Kohm.



### **APPLICATIONS INFORMATION: (Cont.)**

#### **DUTY CYCLE RANGE OF APPLICATION:**



#### **LOAD TRANSIENT CONSIDERATIONS:**

The MUN24AD01-SH module integrates the compensation components to achieve good stability and transient responses. In some applications, adding a 100 pF ceramic cap in parallel with  $R_{\rm FB1}$ .

#### **THERMAL CONSIDERATIONS:**

All of thermal testing condition is complied with JEDEC EIJ/JESD 51 Standards. Therefore, the test board size is 30mm×30mm×1.6mm with 4 layers. The case temperature of module sensing point is shown as FIG.15 then Rth(jchoke-a) is measured with the component mounted on an effective thermal conductivity test board on 0 LFM condition. The MUN24AD01-SH module is designed for using when the case temperature is below 110°C regardless the change of output current, input/output voltage or ambient temperature.



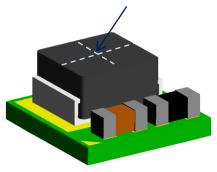


FIG.15 CASE TEMPERATURE SENSING POINT



### **APPLICATIONS INFORMATION: (Cont.)**

#### **REFLOW PARAMETERS:**

Lead-free soldering process is a standard of electronic products production. Solder alloys like Sn/Ag, Sn/Ag/Cu and Sn/Ag/Bi are used extensively to replace the traditional Sn/Pb alloy. Sn/Ag/Cu alloy (SAC) is recommended for this power module process. In the SAC alloy series, SAC305 is a very popular solder alloy containing 3% Ag and 0.5% Cu and easy to obtain. Figure 16 shows an example of the reflow profile diagram. Typically, the profile has three stages. During the initial stage from room temperature to 150°C, the ramp rate of temperature should not be more than 3°C/sec. The soak zone then occurs from 150°C to 200°C and should last for 60 to 120 seconds. Finally, keep at over 217°C for 60 seconds limit to melt the solder and make the peak temperature at the range from 240°C to 250°C. It is noted that the time of peak temperature should depend on the mass of the PCB board. The reflow profile is usually supported by the solder vendor and one should adopt it for optimization according to various solder type and various manufacturers' formulae.

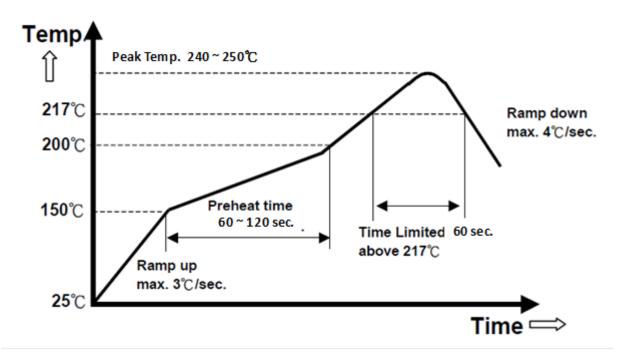
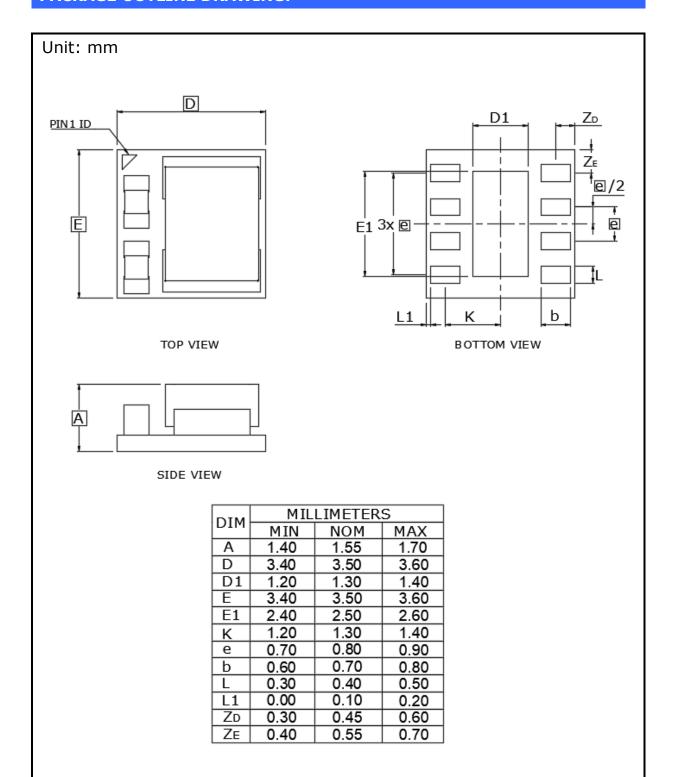


FIG.16 RECOMMENDATION REFLOW PROFILE

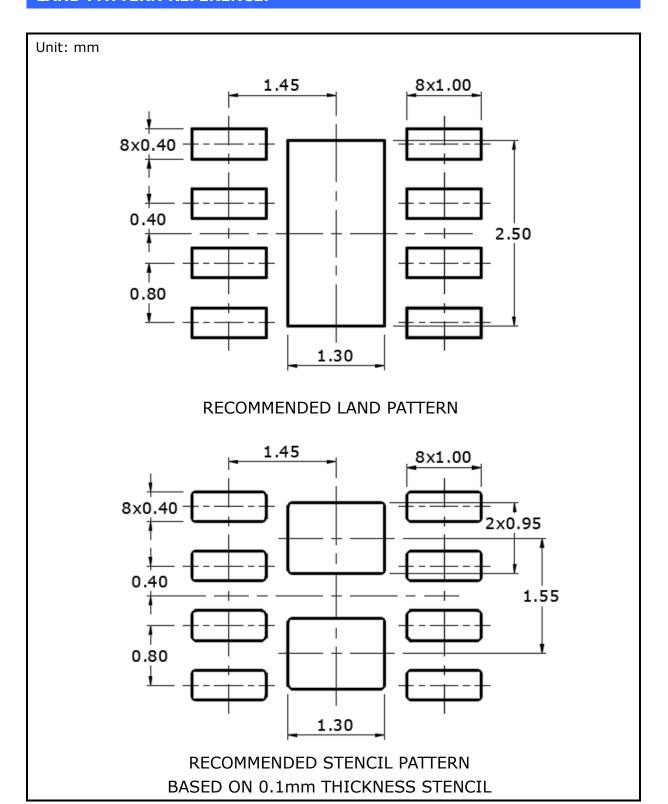


### **PACKAGE OUTLINE DRAWING:**





### **LAND PATTERN REFERENCE:**

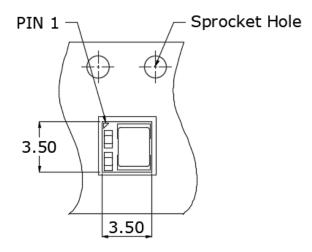




# **PACKING REFERENCE:**

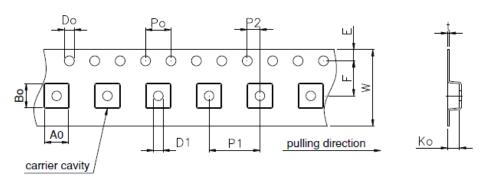
Unit: mm

# **Package In Tape Loading Orientation**



# **Tape Dimension**

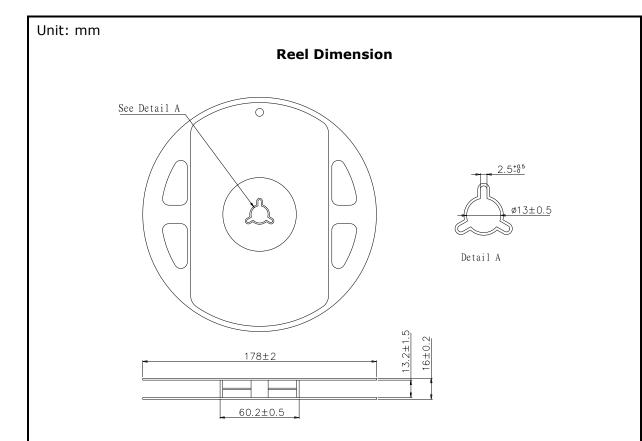
Unit:mm



|                | A0 3.80 ± 0.10 |                  | Е               | 1.75 ± 0.10     |
|----------------|----------------|------------------|-----------------|-----------------|
| B0 3.80 ± 0.10 |                | K0               | $1.88\pm0.10$   |                 |
| F 5.50 ± 0.05  |                | P0               | $4.00 \pm 0.10$ |                 |
|                | W              | $12.0\pm0.30$    | P1              | $8.00\pm0.10$   |
|                | D0             | φ1.5 +0.10/-0.00 | P2              | $2.00 \pm 0.05$ |
|                | D1 φ1.5± 0.10  |                  | t               | 0.25 ± 0.1      |



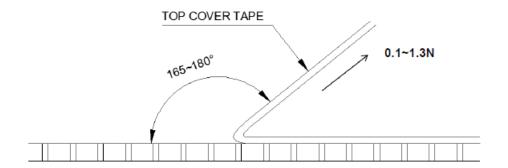
# **PACKING REFERENCE: (Cont.)**



### **Peel Strength of Top Cover Tape**

The peel speed shall be about 300mm/min.

The peel force of top cover tape shall be between 0.1N to 1.3N







# **REVISION HISTORY:**

| Date       | Revision | Changes  |  |
|------------|----------|--|--|
| 2017.11.02 | 00       | Issue initial preliminary datasheet                              |  |
|            |          | 1 · Change maximum output voltage from 6V to 8.5V                |  |
| 2018.06.27 | 01       | 2 · Add page 3 FS and FB to GND maximum ratings                  |  |
|            |          | 3 Change EN low threshold from max. 0.8V to min. 0.4V            |  |
| 2010 02 20 | 03.20 02 | 1 · Change Pin 1 mark to triangle                                |  |
| 2019.03.20 |          | 2 · Update land pattern reference and packing information        |  |
| 2022 02 20 | 3.29 03  | 1 · Update application circuit for EN pin adding a 0.1uF ceramic |  |
| 2022.03.29 |          | capacitor to GND   |  |
| 2022.05.18 | 04       | 1 · Correction title of de-rating curve                          |  |